



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2014-09-02
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giuseppe Vitali Palma	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	7SER*Q93S11Q	B	SH1A	2014-09-02
Amount	UoM	Unit type	ST ECOPACK Grade	
98.438	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	5 - 6 - 0.8	2	flat	
Comment	Package: POWER FLAT 5x6 8L SINGLE. MD valid for STTH5R06DJF-TR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7SER*Q93511Q					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	6.34	mg	supplier	die	Silicon (Si)	7440-21-3		5.947	mg	938013	60414
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.158	mg	24921	1605
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.038	mg	5994	386
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.055	mg	8675	559
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.047	mg	7413	477
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.021	mg	3312	213
die (s)				supplier	passivation	Alcoxsilane	proprietary		0.001	mg	158	10
die (s)				supplier	passivation	Aryl Silicic Acid	proprietary		0.001	mg	158	10
die (s)				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.004	mg	631	41
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.012	mg	1893	122
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.056	mg	8833	569
Leadframe	Copper & its alloys	45.674	mg	supplier	alloy	Copper (Cu)	7440-50-8		44.189	mg	967487	448902
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		1.039	mg	22748	10555
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.063	mg	1379	640
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.054	mg	1182	549
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.327	mg	7159	3322
Leadframe				supplier	metallization	Iron Phoshide(Fe2P)	1310-43-6		0.002	mg	44	20
Soft solder	Other Organic Materials	5.228	mg	JIG Table R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.992	mg	954858	50712
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.131	mg	25057	1331
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.105	mg	20084	1067
Bonding	Other inorganic materials	1.695		supplier	Ribbon	Aluminium (Al)	7429-90-5		1.695	mg	1000000	17219
encapsulation	Other Organic Materials	39.476	mg	supplier	mold compound	Silica, vitreous	60676-86-0		36.556	mg	926031	371361
encapsulation				supplier	mold compound	epoxy resin	85954-11-6		1.579	mg	39999	16041
encapsulation				supplier	mold compound	phenol resin	26834-02-6		1.184	mg	29993	12028
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.157	mg	3977	1595
connections coating	Solder	0.025	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.025	mg	1000000	254